



## Material Content Data Sheet



<b>Sales Product Name</b>		BSZ440N10NS3 G		<b>Issued</b>		18. May 2016		
<b>MA#</b>		MA001493842						
<b>Package</b>		PG-TSDSON-8-1		<b>Weight*</b>		36.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.830	2.30	2.30	22961	22961
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		65	
	non noble metal	zinc	7440-66-6	0.009	0.03		262	
	non noble metal	iron	7439-89-6	0.189	0.52		5239	
wire	non noble metal	copper	7440-50-8	7.689	21.27	21.83	212744	218310
	non noble metal	copper	7440-50-8	0.040	0.11	0.11	1101	1101
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1030
	plastics	epoxy resin	-	1.918	5.31		53071	
	inorganic material	silicondioxide	60676-86-0	16.667	46.13	51.54	461150	515251
leadfinish	non noble metal	tin	7440-31-5	0.370	1.02	1.02	10239	10239
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2236	2236
solder	noble metal	silver	7440-22-4	0.028	0.08		780	
	non noble metal	tin	7440-31-5	0.023	0.06		624	
	non noble metal	lead	7439-92-1	1.078	2.98	3.12	29814	31218
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		33	
	non noble metal	zinc	7440-66-6	0.005	0.01		130	
	non noble metal	iron	7439-89-6	0.094	0.26		2600	
heat sink CLIP	non noble metal	copper	7440-50-8	3.816	10.56	10.83	105582	108345
	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		108	
	non noble metal	iron	7439-89-6	0.078	0.22		2168	
	non noble metal	copper	7440-50-8	3.182	8.80	9.03	88036	90339
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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